

Special Issue

Recent Advances of Wearable and Flexible Sensor Devices and Their Future Prospects

Message from the Guest Editors

Recently, wearable and flexible sensors have attracted tremendous research interest due to their promising applications in health-care monitoring, human-machine interface, electronic skin (e-skin), and soft robotics. In this Special Issue, we focus on the recent advancements, current challenges, and new opportunities of wearable and flexible physical and electrochemical sensors. We invite emerging investigators, experts, and researchers working on physical sensors (e.g., pressure, strain, temperature, humidity, ECG, etc.) and electrochemical biosensors to contribute their insightful ideas through commentaries, perspectives, future outlooks, and reviews. The developments focused on novel sensing materials, transduction principles, sensor design strategies, and their unique applications are highly encouraged to submit in the formats of either full-length articles or short communications. Looking forward to the prospects and attention to the key challenges, we expect the wearable and flexible sensor devices will continue to spark a greater impact in disease diagnosis, e-skin, prosthetic body organs, and body sensor networks.

Guest Editors

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Deadline for manuscript submissions

closed (31 October 2023)



Micromachines

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Impact Factor 3.0
CiteScore 6.0
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